

a first housing extending around said chip and fixed relative to said window.

2. (Amended) The package of claim 1, wherein said chip is hermetically sealed by said window and said first housing.

3. (Amended) The package of claim 2, wherein said first housing is sealed to said window at the periphery of said window by a sealing-type material.

5. (Amended) The package of claim 4, wherein said chip comprises a photonic device having one or more electrical terminals.

6. (Amended) The package of claim 5, wherein at one of said one or more electrical terminals is connected to at least one of the at least one conductive trace.

7. (Amended) The package of claim 6, further comprising a second housing situated adjacent to a second side of said window.

8. (Amended) The package of claim 7, further comprising a ferrule having at least one optical fiber, which is placed adjacent said second side of said window.

9. (Amended) The package of claim 8, further comprising a lens formed on or in said window.

10. (Amended) The package of claim 9, wherein said ferrule is accepted by an opening in said second housing

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11. (Amended) The package of claim 10, wherein an end of said optical fiber is proximate to said window so that light from the fiber can go through the optical fiber and said window to the photonic device, and/or so that light from the photonic device can go through said window and the least one optical fiber.

12. (Amended) A chip-scale package for photonic devices, comprising:
a first housing;
a chip attached relative to said first housing; and
a window attached relative to said first housing.

13. (Amended) The package of claim 12, further comprising:
at least one conductive trace formed on said window; and
the at least one conductive trace is connected to said chip and to a pad of said first housing.

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22. (Amended) The package of claim 21, wherein said window has at least one lens situated between the at least one photonic device and the at least one optical waveguide.

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24. (Amended) A hermetic chip-scale package comprising:

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a first housing;

an integrated circuit mounted within said first housing;

a window secured relative to said first housing; and

wherein:

said integrated circuit has at least one photonic device; and

said first housing and said window form a hermetically sealed enclosure around
said integrated circuit.

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26. (Amended) The package of claim 25, comprising a conductor
connected to the at least one conductive trace, for providing a connection from the at least
one conductive trace external to the hermetically sealed enclosure.

27. (Amended) The package of claim 26, further comprising a second
housing situated adjacent to said window, wherein said second housing has at least one
alignment feature.

28. (Amended) The package of claim 27, further comprising a plug having
an at least one optical waveguide, wherein said plug fits into said second housing and is
aligned with the at least one alignment feature such that one end of the at least one optical
waveguide is proximate to said window.

29. (Amended) The package of claim 28, wherein the one end of the at
least one optical waveguide is aligned with the at least one photonic device.

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30 . (Amended) The package of claim 29, further comprising at least one pin securing said plug in said second housing.

31 . (Amended) The package of claim 28, wherein the at least one photonic device is a VCSEL.

32 . (Amended) The package of claim 29, wherein:
said first housing is composed of ceramic; and
said window is composed of quartz.

33 . (Amended) A chip-scale package for electronic devices, comprising:
a transparent window having at least one conductive trace patterned on a surface
of said window;
a semiconductor chip fixed relative to said window having at least one terminal
connected to the at least one conductive trace;
a first housing surrounding said chip and affixed to said window; and
a conductive path from the at least conductive trace to an at least one pad on an
external surface of said enclosure.

34 . (Amended) The package of claim 33, wherein said chip comprises a photonic device.

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35 . (Amended) The package of claim 34, wherein said window has at least one feature on the surface of said window for alignment.

36 . (Amended) The package of claim 34, wherein the conductive path is partially embedded in said first housing.

37 . (Amended) The package of claim 36, wherein the conductive path is connected on one end to a pad on the external surface of said first housing.

38 . (Amended) The package of claim 37, wherein said conductive path is connected on another end to another pad which is connected to the at least one said conductive trace on said window.

39 . (Amended) The package of claim 38, wherein said first housing is sealed to said window at a periphery of said window.

40 . (Amended) The package of claim 39, wherein said first housing is sealed to said window at the periphery of said window by a solder-type material.

41 . (Amended) The package of claim 39, wherein said first housing is sealed to said window at the periphery of said window by an adhesive-type material.

42. (Amended) The package of claim 39, wherein said chip is hermetically sealed by said window and said first housing.

43. (Amended) The package of claim 39, wherein said chip is environmentally sealed by said window and said first housing.

44. (Amended) The package of claim 42, wherein said window has at least one refractive optical element on the surface of said window.

45. (Amended) The package of claim 43, wherein said window has at least one refractive optical element on the surface of said window.

46. (Amended) The package of claim 42, wherein said window has at least one diffractive optical element on the surface of said window.

47. (Amended) The package of claim 43, wherein said window has at least one diffractive optical element on the surface of said window.

48. (Amended) The package of claim 35, further comprising a second housing attached to said first housing.

49. (Amended) The package of claim 48, wherein said second housing is mechanically registered to said first housing by the at least one feature on the surface of said window.

50. (Amended) The package of claim 49, further comprising a ferrule having at least one optical waveguide.

51. (Amended) The package of claim 50, wherein the at least one optical waveguide is proximate to said window so that light from the waveguide can pass through said window to the at least one photonic device, and/or so that light from the photonic device can go through said window and to the at least one optical waveguide.

52. (Amended) The package of claim 51, wherein said window has at least one lens situated between the at least one photonic device and said at least one optical waveguide.

53. (Amended) The package of claim 52, wherein the at least one optical waveguide is an optical fiber.

54. (Amended) The package of claim 51, further comprising at least one pin securing said ferrule to said first housing.